

Title (en)
INVERTER SURGE-RESISTANT INSULATED WIRE AND METHOD OF PRODUCING SAME

Title (de)
GEGEN WECHSELRICHTERÜBERSpannung RESISTENTER, ISOLIERTER DRAHT UND VERFAHREN ZUR HERSTELLUNG DAVON

Title (fr)
CÂBLE ISOLÉ D'INVERSEUR RÉsISTANT AUX SURTENSIONS AINSI QUE PROCÉDÉ DE FABRICATION ASSOCIÉ

Publication
EP 2843668 B1 20200101 (EN)

Application
EP 13858435 A 20131120

Priority
• JP 2012263749 A 20121130
• JP 2013081300 W 20131120

Abstract (en)
[origin: US2015027748A1] An inverter surge-resistant insulated wire, having at least one baked enamel layer around the outer periphery of a conductor having a rectangular cross-section, at least one extrusion-coated resin layer around the outer side thereof, and an adhesive layer having a thickness of 2 to 20 μm between the baked enamel layer and the extrusion-coated resin layer, wherein each of the at least one extrusion-coated resin layer on the adhesive layer is formed by the same resin, a cross-sectional shape of the baked enamel layer and the extrusion-coated resin layer in the cross-section of the inverter surge-resistant insulated wire is rectangular, and in the cross-sectional shape formed by the baked enamel layer and the extrusion-coated resin layer surrounding the conductor in a cross-sectional view, at least a pair of two sides of two pairs of two sides opposing at the upper side and the downside or at the right side and the left side with respect to the conductor each meet the conditions that a total thickness of the baked enamel layer and the extrusion-coated resin layer is 80 μm or more, a thickness of the baked enamel layer is 60 μm or less, a thickness of the extrusion-coated resin layer is 200 μm or less, and the resin of the extrusion-coated resin layer has a melting point of 300° C. or more and 370° C. or less, and a method of producing the inverter surge-resistant insulated wire comprising forming adhesive layer on the outer periphery of the baked enamel layer, and then extruding a thermoplastic resin for forming the extrusion-coated resin layer on the adhesive layer thereby to contact with the adhesive layer, the thermoplastic resin becoming a molten state at a higher temperature than a glass transition temperature of the resin that is used for the adhesive layer.

IPC 8 full level
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CPC (source: EP US)
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Cited by
EP3043355A4; EP3103120A4; EP3441983A4; EP4080525A4; US10319491B2; US10566109B2; WO2023047083A2

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